

MiniSKiiP® 2

## Sixpack

### SKiiP 25AC12T4V25

#### Features\*

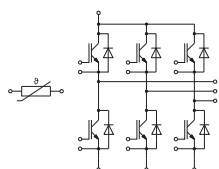
- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Typical Applications

- Inverter up to 26 kVA
- Typical motor power 15 kW

#### Remarks

- $V_{CEsat}$ ,  $V_F$  = chip level value
- Case temp. limited to  $T_C = 125^\circ\text{C}$  max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_j \leq 150$  (recomm.  $T_{op} = -40 \dots +150^\circ\text{C}$ )
- Dynamic test results for  $V_{CC} = 600\text{V}$ ,  $R_{Gon/off} = 12\Omega$ ,  $I_C = 50\text{A}$ ,  $V_{GE} = \pm 15\text{V}$ :  $E_{on} = 5.6\text{mJ}$ ,  $E_{off} = 6.1\text{mJ}$ ,  $E_{rr} = 3.3\text{mJ}$ ,  $di/dt_{on} = 1440\text{A}/\mu\text{s}$ ,  $t_{don} = 58\text{ns}$ ,  $t_r = 43\text{ns}$ ,  $di/dt_{off} = 600\text{A}/\mu\text{s}$ ,  $t_{doff} = 370\text{ns}$ ,  $t_f = 65\text{ns}$



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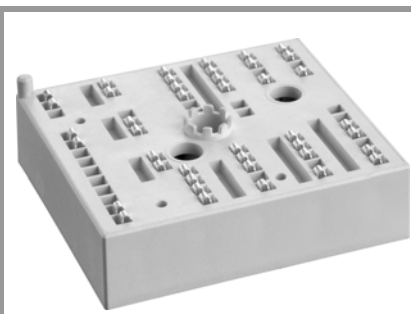
#### Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1200	V
I <sub>C</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	68	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	55	A
I <sub>C</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	t.b.d.	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	t.b.d.	A
I <sub>Cnom</sub>			50	A
I <sub>CRM</sub>			150	A
V <sub>GES</sub>			-20 ... 20	V
t <sub>psc</sub>	V <sub>CC</sub> = 800 V V <sub>GE</sub> ≤ 15 V V <sub>CES</sub> ≤ 1200 V	T <sub>j</sub> = 150 °C	10	μs
T <sub>j</sub>			-40 ... 175	°C
Inverse - Diode				
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1200	V
I <sub>F</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	60	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	48	A
I <sub>F</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	t.b.d.	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	t.b.d.	A
I <sub>FRM</sub>			100	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180°, T <sub>j</sub> = 150 °C		270	A
T <sub>j</sub>			-40 ... 175	°C
Module				
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C, 20 A per spring		60	A
T <sub>stg</sub>	module without TIM		-40 ... 125	°C
V <sub>isol</sub>	AC sinus 50 Hz, t = 1 min		2500	V

#### Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
<b>Inverter - IGBT</b>					
$V_{CE(sat)}$	$I_C = 50\text{ A}$ $V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$	1.85	2.10	V
		$T_j = 150^\circ\text{C}$	2.20	2.40	V
$V_{CE0}$	chiplevel	$T_j = 25^\circ\text{C}$	0.80	0.90	V
		$T_j = 150^\circ\text{C}$	0.70	0.80	V
$r_{CE}$	$V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$	21	24	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	30	32	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 1.7\text{ mA}$	5	5.8	6.5	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ , $V_{CE} = 1200\text{ V}$ , $T_j = 25^\circ\text{C}$			1	mA
$C_{ies}$	$V_{CE} = 25\text{ V}$	$f = 1\text{ MHz}$	2.77		nF
$C_{oes}$	$V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	0.21		nF
$C_{res}$		$f = 1\text{ MHz}$	0.16		nF
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		283		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		4.0		$\Omega$
$t_{d(on)}$	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$	45		ns
$t_r$	$I_C = 22\text{ A}$ $R_{Gon} = 12\Omega$	$T_j = 150^\circ\text{C}$	19		ns
		$T_j = 150^\circ\text{C}$	3.4		mJ
$E_{on}$	$R_{Goff} = 1\Omega$	$T_j = 150^\circ\text{C}$	3.4		mJ
$t_{d(off)}$	$di/dt_{on} = 1640\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	480		ns
$t_f$	$di/dt_{off} = 320\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	44		ns
$E_{off}$	$V_{GE} = +15/0\text{ V}$	$T_j = 150^\circ\text{C}$	3.1		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$		0.71		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$		t.b.d.		K/W

# SKiiP 25AC12T4V25



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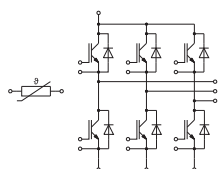
#### Typical Applications

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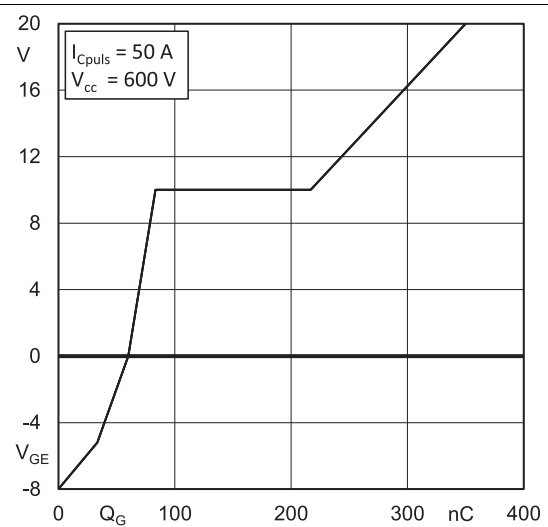
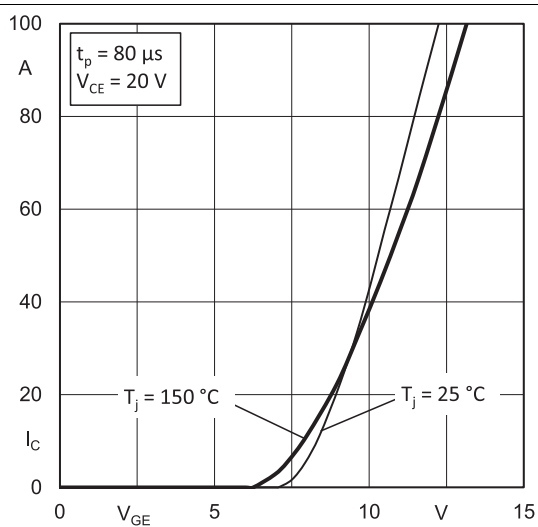
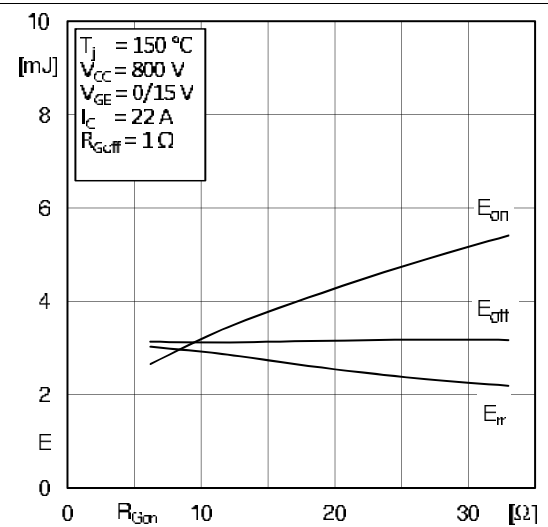
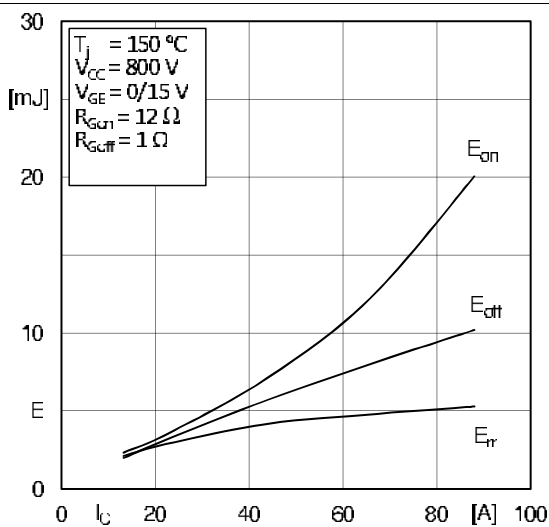
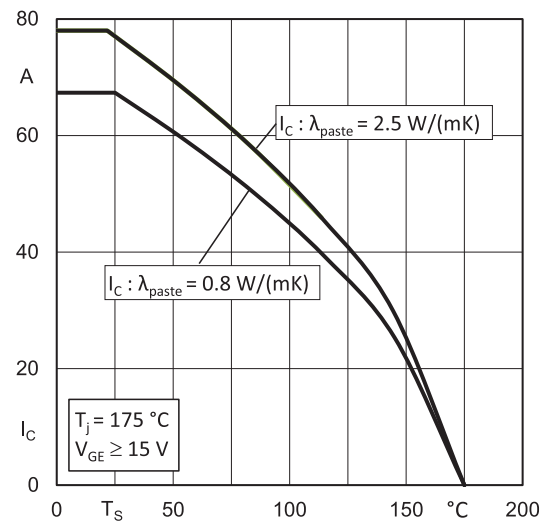
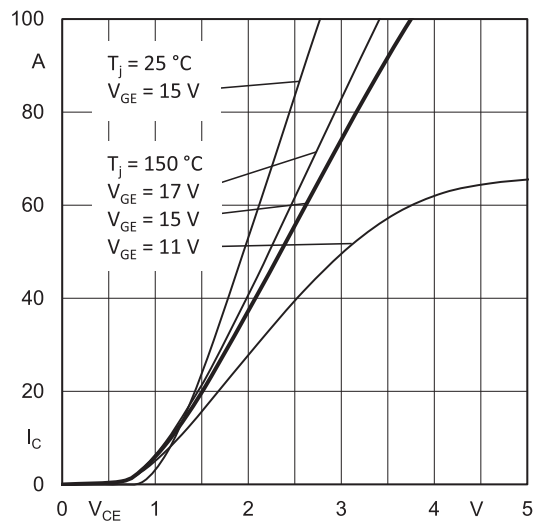
#### Remarks

- $V_{CEsat}$ ,  $V_F$  = chip level value
- Case temp. limited to  $T_C = 125^\circ\text{C}$  max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_j \leq 150$  (recomm.  $T_{op} = -40 \dots +150^\circ\text{C}$ )
- Dynamic test results for  $V_{CC} = 600\text{V}$ ,  $R_{Gon/off} = 12\Omega$ ,  $I_C = 50\text{A}$ ,  $V_{GE} = \pm 15\text{V}$ :  $E_{on} = 5.6\text{mJ}$ ,  $E_{off} = 6.1\text{mJ}$ ,  $E_{rr} = 3.3\text{mJ}$ ,  $di/dt_{on} = 1440\text{A}/\mu\text{s}$ ,  $t_{don} = 58\text{ns}$ ,  $t_r = 43\text{ns}$ ,  $di/dt_{off} = 600\text{A}/\mu\text{s}$ ,  $t_{doff} = 370\text{ns}$ ,  $t_f = 65\text{ns}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 50 A	T <sub>j</sub> = 25 °C		2.22	2.54	V
	V <sub>GE</sub> = 0 V chiplevel	T <sub>j</sub> = 150 °C		2.18	2.50	V
V <sub>F0</sub>	chiplevel	T <sub>j</sub> = 25 °C		1.30	1.50	V
		T <sub>j</sub> = 150 °C		0.90	1.10	V
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		18	21	mΩ
		T <sub>j</sub> = 150 °C		26	28	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 22 A	T <sub>j</sub> = 150 °C		0		A
Q <sub>rr</sub>	di/dt <sub>off</sub> = 1680 A/μs	T <sub>j</sub> = 150 °C		5.5		μC
E <sub>rr</sub>	V <sub>GE</sub> = +15/0 V	T <sub>j</sub> = 150 °C		2.9		mJ
	V <sub>CC</sub> = 800 V					
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =0.8 W/(mK)			0.95		K/W
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =2.5 W/(mK)			t.b.d.		K/W
Module						
L <sub>CE</sub>				-		nH
M <sub>s</sub>	to heat sink		2		2.5	Nm
w				55		g
Temperature Sensor						
R <sub>100</sub>	T <sub>r</sub> =100°C (R <sub>25</sub> =1000Ω)			1670 ± 3%		Ω
R <sub>(T)</sub>	R <sub>(T)</sub> =1000Ω[1+A(T-25°C)+B(T-25°C) <sup>2</sup> ] , A = 7.635*10 <sup>-3</sup> °C <sup>-1</sup> , B = 1.731*10 <sup>-5</sup> °C <sup>-2</sup>					



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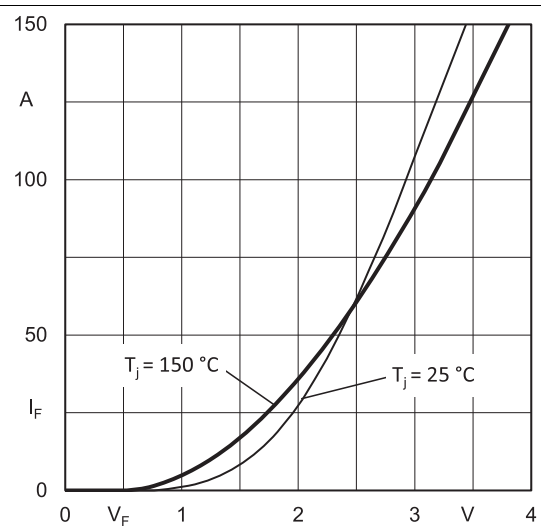
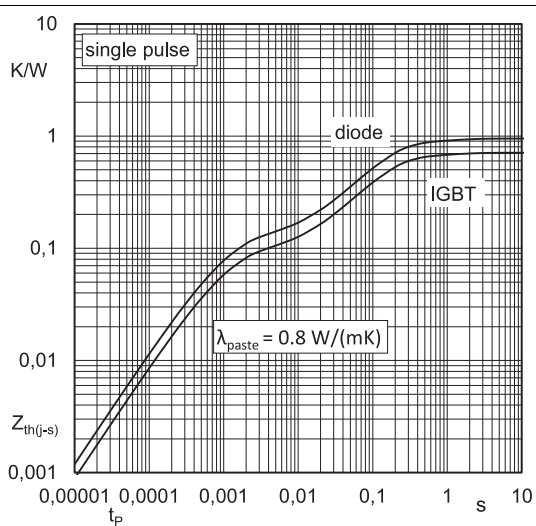
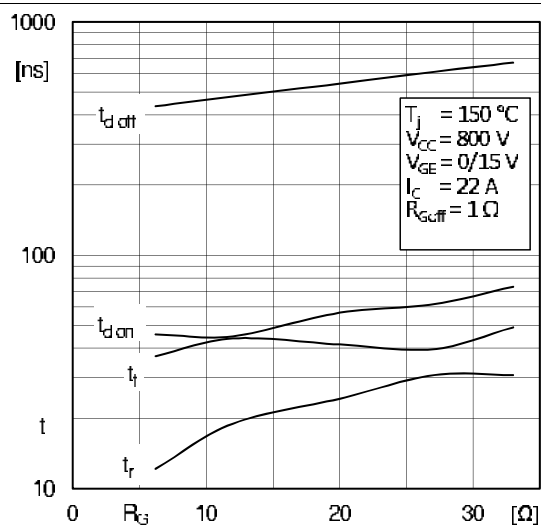
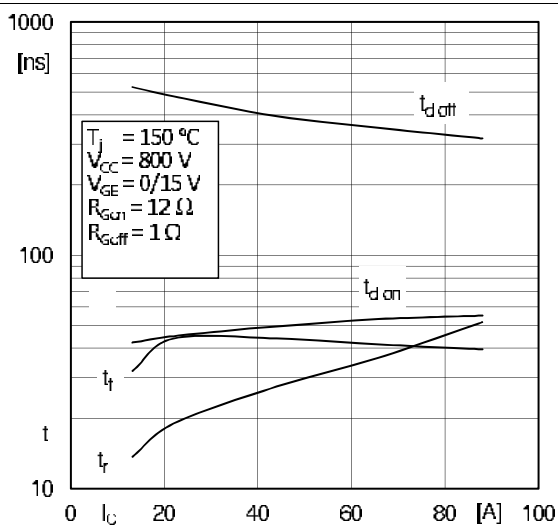


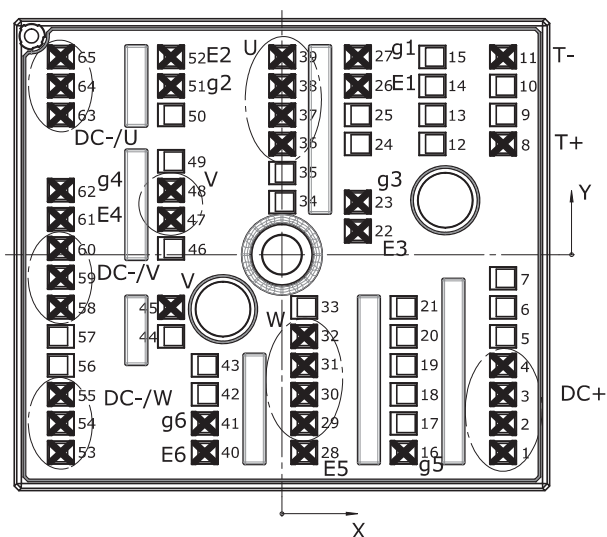
Fig. 11: Typ. CAL diode peak reverse recovery current

Fig. 12: Typ. CAL diode recovery charge

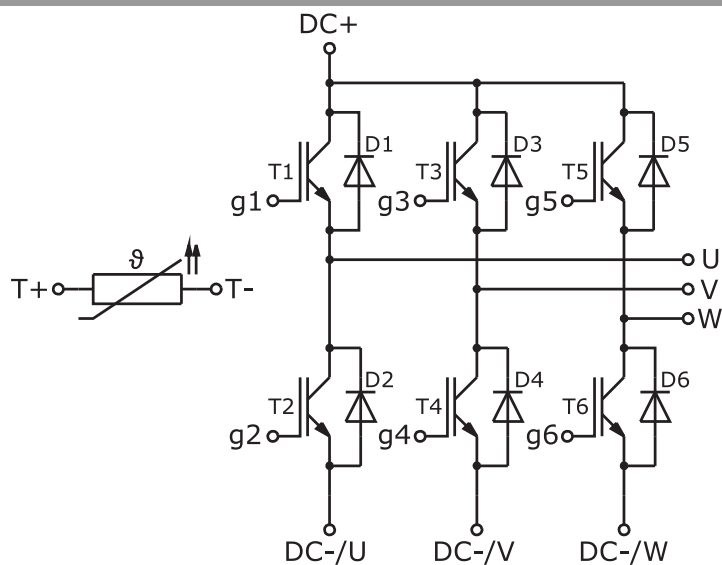
## SKiiP 25AC12T4V25

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,80	DC+	23	8,38	5,80	g3	45	-12,23	-5,80	V
2	24,38	-18,60	DC+	24	8,38	12,20		46	-12,23	0,70	
3	24,38	-15,40	DC+	25	8,38	15,40		47	-12,23	3,90	V
4	24,38	-12,20	DC+	26	8,38	18,60	E1	48	-12,23	7,10	V
5	24,38	-9,00		27	8,38	21,80	g1	49	-12,23	10,30	
6	24,38	-5,80		28	2,46	-21,80	E5	50	-12,23	15,40	
7	24,38	-2,60		29	2,46	-18,60	W	51	-12,23	18,60	g2
8	24,38	12,20	T+	30	2,46	-15,40	W	52	-12,23	21,80	E2
9	24,38	15,40		31	2,46	-12,20	W	53	-24,38	-21,80	DC-/W
10	24,38	18,60		32	2,46	-9,00	W	54	-24,38	-18,60	DC-/W
11	24,38	21,80	T-	33	2,46	-5,80		55	-24,38	-15,40	DC-/W
12	16,58	12,20		34	0,03	5,80		56	-24,38	-12,20	
13	16,58	15,40		35	0,03	9,00		57	-24,38	-9,00	
14	16,58	18,60		36	0,03	12,20	U	58	-24,38	-5,80	DC-/V
15	16,58	21,80		37	0,03	15,40	U	59	-24,38	-2,50	DC-/V
16	13,42	-21,80	g5	38	0,03	18,60	U	60	-24,38	0,70	DC-/V
17	13,42	-18,60		39	0,03	21,80	U	61	-24,38	3,90	E4
18	13,42	-15,40		40	-8,51	-21,80	E6	62	-24,38	7,10	g4
19	13,42	-12,20		41	-8,51	-18,60	g6	63	-24,38	15,40	DC-/U
20	13,42	-9,00		42	-8,51	-15,40		64	-24,38	18,60	DC-/U
21	13,42	-5,80		43	-8,51	-12,20		65	-24,38	21,80	DC-/U
22	8,38	2,60	E3	44	-12,23	-9,00					

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

## **\*IMPORTANT INFORMATION AND WARNINGS**

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